8mm (0.32INCH) SINGLE DIGIT NUMERIC DIS-PLAY

Part Number: SA32-11SRWA Supe

Super Bright Red

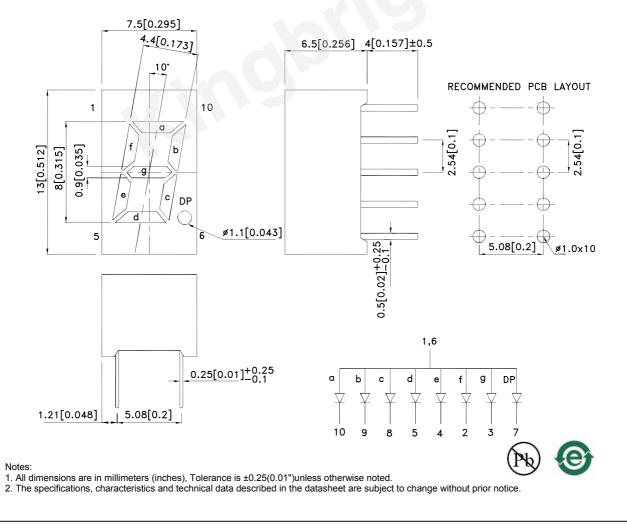
Features

- 0.32 inch digit height.
- Low current operation.
- Excellent character appearance.
- High light output.
- Easy mounting on P.C. boards or sockets.
- Mechanically rugged.
- Standard : gray face, white segment.
- RoHS compliant.

Description

The Super Bright Red source color devices are made with Gallium Aluminum Arsenide Red Light Emitting Diode.

Package Dimensions& Internal Circuit Diagram



SPEC NO: DSAB4361 APPROVED: Wynec REV NO: V.13A CHECKED: Joe Lee DATE: JUN/18/2016 DRAWN: L.T.Zhang PAGE: 1 OF 6 ERP: 1301000281

Selection Guide Part No.	Emitting Color (Material)	Lens Type	lv (ucd) [1] @ 10mA		Description
			Min.	Тур.	
SA32-11SRWA	Super Bright Red (GaAlAs)	White Diffused	14000	37000	Common Anode, Rt.Hand Decimal.
			*5600	*10000	

Notes:

1. Luminous intensity / luminous Flux: +/-15%. * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	655		nm	I⊧=10mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	I⊧=10mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	IF=10mA
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Super Bright Red	1.8	2.5	V	IF=10mA
IR	Reverse Current	Super Bright Red		10	uA	VR=5V

Notes: 1. Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3. Wavelength value is traceable to CIE127-2007 standards.

Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

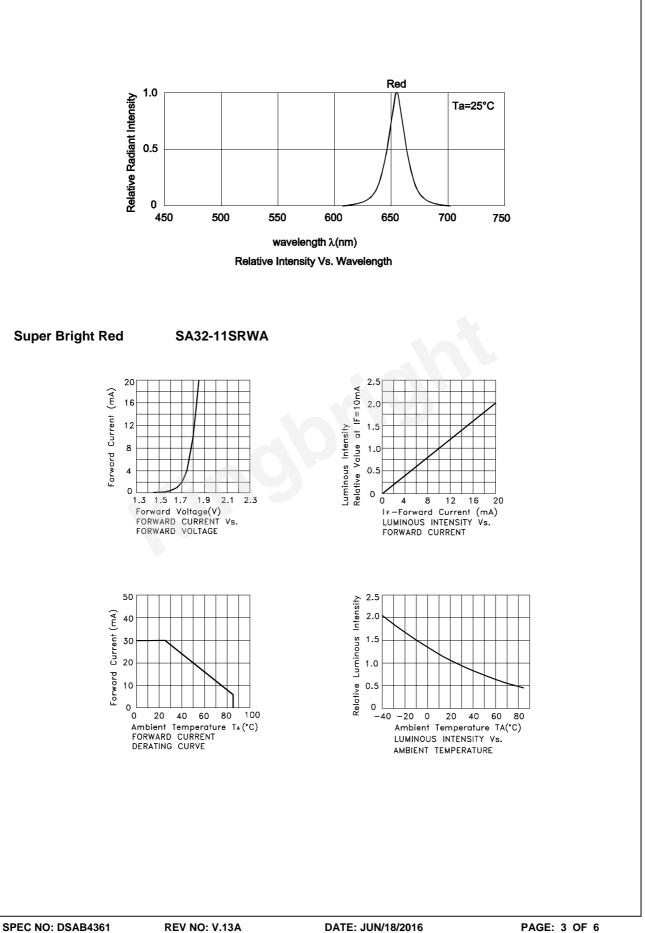
Parameter	Values	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	155	mA		
Reverse Voltage	5	V		
Operating / Storage Temperature	-40°C To +85°C			
Lead Solder Temperature[2]	260°C For 3-5 Seconds			

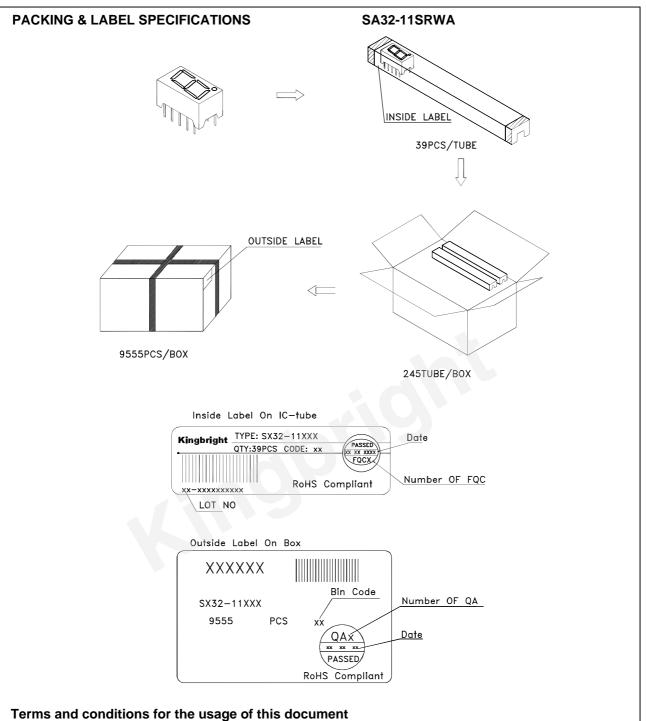
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

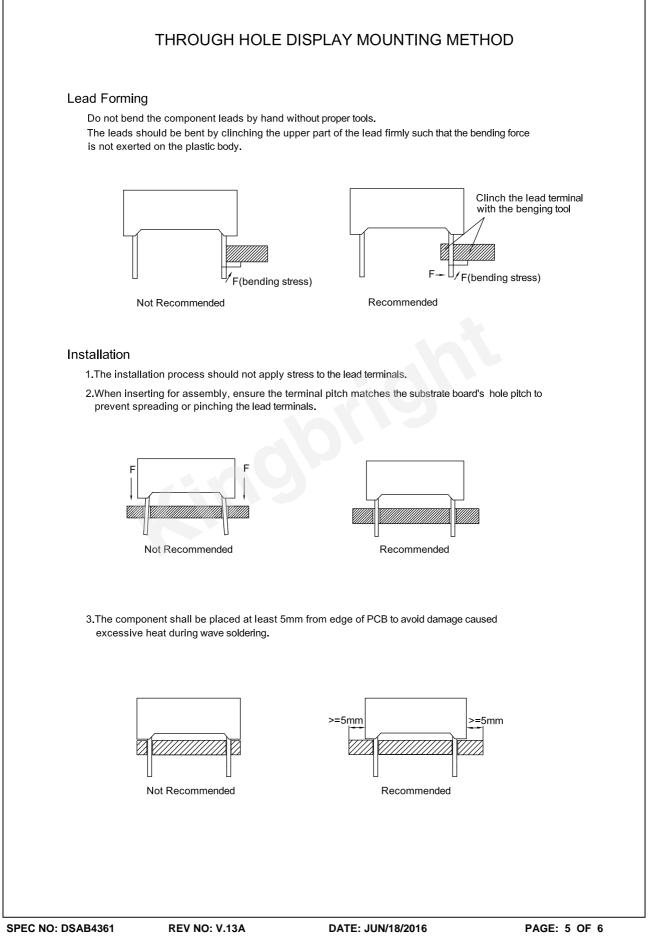
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



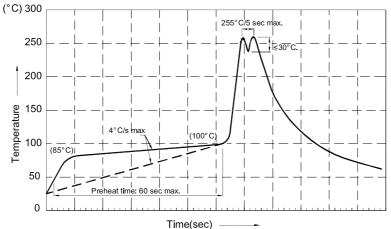


- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- 2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
- 3. When using the products referenced in this document, please make sure the product is being operated within the environmental and electrical limits specified in the datasheet. If customer usage exceeds the specified limits, Kingbright will not be responsible for any subsequent issues.
- 4. The information in this document applies to typical usage in consumer electronics applications. If customer's application has special reliability requirements or have life-threatening liabilities, such as automotive or medical usage, please consult with Kingbright representative for further assistance.
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- 6. All design applications should refer to Kingbright application notes available at http://www.kingbright.com/application_notes

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Recommended Wave Soldering Profiles:



Notes:

- 1.Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2 Peak wave soldering temperature between 245° C ~ 255° C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85° C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering process.
- 5.SAC 305 solder alloy is recommended.
- 6.No more than one wave soldering pass.
- 7.During wave soldering, the PCB top-surface temperature should be kept below 105°C.

Soldering General Notes:

- 1.Through-hole displays are incompatible with reflow soldering.
- 2.If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

CLEANING

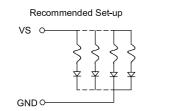
1.Mild "no-clean" fluxes are recommended for use in soldering.

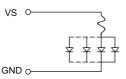
- 2.If cleaning is required, Kingbright recommends to wash components with water only.
- Do not use harsh organic solvents for cleaning because they may damage the plastic parts .
- 3. The cleaning process should take place at room temperature and the devices should not be washed for more than one minute.
- 4. When water is used in the cleaning process, immediately remove excess moisture from the component with forced-air drying afterwards.

CIRCUIT DESIGN NOTES

1.Protective current-limiting resistors may be necessary to operate the LEDs within the specified range.

2.LEDs mounted in parallel should each be placed in series with its own current-limiting resistor.





invalid Set-up

- 3. The driving circuit should be designed to protect the LED against reverse voltages and transient voltage spikes when the circuit is powered up or shut down.
- 4. The safe operating current should be chosen after considering the maximum ambient temperature of the operating environment.
- 5. Prolonged reverse bias should be avoided, as it could cause metal migration, leading to an increase in leakage current or causing a short circuit.